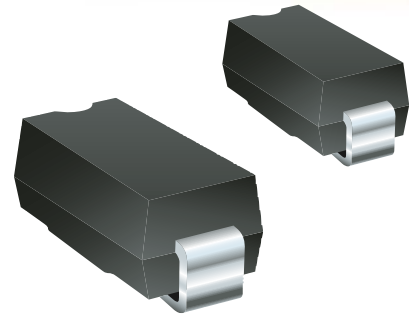




Product Change Notification

CHIP DIODES

Bourns Rep District Sales Managers
Bourns Rep Distributor Managers
Corporate Distributor Product Managers
Americas Sales Team
Asia Sales Team
Europe Sales Team
Bourns Customers



January, 2009

Bourns® Diode Product Line Addition of Back-end Package Assembly Location

Bourns is adding an additional back-end package assembly location for the assembly of our diode products. The Diode Product Line strategy is always to have two (2) qualified package assembly locations to avoid any production line downtime and for continued delivery of product to our customers. Below are the affected Bourns part numbers that are currently packaged and assembled in Taiwan:

[CD214L-TxxALF Series](#)

[CD214L-TxxCALF Series](#)

To increase back-end package assembly capacity while reducing lead times, Bourns will add the second SMC back-end package assembly location in China for the above part numbers for continued secure supply chain management and delivery support to our customers.

Samples of the above part numbers using the second SMC back-end package assembly location in China are now available. Reliability data on units packaged and assembled at the new location is now available on request. Mass production using the second SMC back-end package assembly location in China is available.

Bourns is issuing 90 days notice that mass production at the alternative back-end package assembly location will start 31st March 2009.